



NSAI
Standards

Irish Standard
I.S. EN 61188-7:2017

Printed boards and printed board assemblies - Design and use - Part 7: Electronic component zero orientation for CAD library construction

I.S. EN 61188-7:2017

Incorporating amendments/corrigenda/National Annexes issued since publication:

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National Foreword

I.S. EN 61188-7:2017 is the adopted Irish version of the European Document EN 61188-7:2017, Printed boards and printed board assemblies - Design and use - Part 7: Electronic component zero orientation for CAD library construction

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EUROPEAN STANDARD

EN 61188-7

NORME EUROPÉENNE

EUROPÄISCHE NORM

June 2017

ICS 31.180

Supersedes EN 61188-7:2009

English Version

**Printed boards and printed board assemblies - Design and use -
Part 7: Electronic component zero orientation for CAD library
construction
(IEC 61188-7:2017)**

Cartes imprimées et cartes imprimées équipées -
Conception et utilisation - Partie 7: Orientation nulle des
composants électroniques pour l'élaboration de la
bibliothèque CAO
(IEC 61188-7:2017)

Leiterplatten und Flachbaugruppen - Konstruktion und
Anwendung - Teil 7: Nullorientierung elektronischer
Bauelemente für CAD-Bibliotheksaufbau
(IEC 61188-7:2017)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

EN 61188-7:2017

European foreword

The text of document 91/1382/CDV, future edition 2 of IEC 61188-7, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61188-7:2017.

The following dates are fixed:

- latest date by which the document has to be (dop) 2018-02-15
implemented at national level by
publication of an identical national
standard or by endorsement
- latest date by which the national (dow) 2020-05-15
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Annex ZA

(normative)

**Normative references to international publications
with their corresponding European publications**

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NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here:
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<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
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IEC 61188-7

Edition 2.0 2017-04

INTERNATIONAL STANDARD



**Printed boards and printed board assemblies – Design and use –
Part 7: Electronic component zero orientation for CAD library construction**



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IEC 61188-7

Edition 2.0 2017-04

INTERNATIONAL STANDARD



**Printed boards and printed board assemblies – Design and use –
Part 7: Electronic component zero orientation for CAD library construction**

INTERNATIONAL
ELECTROTECHNICAL
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CONTENTS

FOREWORD.....	3
INTRODUCTION.....	5
1 Scope.....	6
2 Normative references	6
3 Terms and definitions	6
4 Basic rules	6
4.1 Common rules.....	6
4.2 General basic rules	6
4.3 Level A basic rule	7
4.4 Level B basic rule	7
4.5 File description definition	7
4.6 Component orientations	8
5 Origin point of land pattern	18
5.1 General.....	18
5.2 Surface mount components.....	18
5.3 Through-hole leaded components	19
6 Land pattern to footprint comparison	19
7 Components with one terminal.....	20
7.1 Surface mount components.....	20
7.2 Through-hole leaded components	20
Figure 1 – Example of level A orientation concepts	8
Figure 2 – Connector and switch library symbol examples	19
Figure 3 – Through-hole components with terminal point of origin orientation	19
Figure 4 – Circular or square one-terminal component	20
Figure 5 – Rectangular or oval one-terminal component	20
Figure 6 – Surface mount components with one lead offset.....	20
Table 1 – Discrete component land pattern conventions	9
Table 2 – Diode and transistor land pattern conventions	10
Table 3 – Transistor and IC land pattern conventions	11
Table 4 – Integrated circuit packages land pattern conventions	12
Table 5 – Integrated circuit packages land pattern conventions	14
Table 6 – BGA land pattern conventions	15
Table 7 – Resistor array and connector land pattern conventions.....	16
Table 8 – Level A land pattern convention summary	17
Table 9 – Level B land pattern convention summary	18

INTERNATIONAL ELECTROTECHNICAL COMMISSION

PRINTED BOARDS AND PRINTED BOARD ASSEMBLIES – DESIGN AND USE –

Part 7: Electronic component zero orientation for CAD library construction

FOREWORD

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International Standard IEC 61188-7 has been prepared by IEC technical committee 91: Electronics assembly technology.

This second edition cancels and replaces the first edition published in 2009. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) Figure 1 has been corrected;
- b) the term "rectangle" has generally been replaced by "polygon";
- c) level B has been indicated as preferred level for new libraries.

The text of this International Standard is based on the following documents:

CDV	Report on voting
91/1382/CDV	91/1428/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of the IEC 61188 series, under the general title *Printed boards and printed board assemblies – Design and use*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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INTRODUCTION

One of the factors of establishing a CAD library component description and land pattern standard is to adopt a fixed zero component orientation so that all CAD images are built with the same rotation for the purpose of assembly machine automation.

The land pattern standards clearly define all the properties necessary for standardization and acceptability of a one world CAD library. The main objective in defining a one world CAD library is to achieve the highest level of electronic product development automation. This encompasses all the processes involved from engineering to PCB layout to fabrication, assembly and test. The data format standards need this type of consistency in order to meet the efficiency that electronic data transfer can bring to the industry.

Many large firms have spent millions of dollars creating and implementing their own unique standards for their own electronic product development automation. These standards are proprietary to each firm and are not openly shared with the rest of the industry. This has resulted in massive duplication of effort, costing the industry millions of man hours in waste and creating industry chaos and global non-standardization.

The main purpose of creating the land pattern standards is to achieve reliable solder joint formation platforms; the reason for developing the data transfer structure is to improve the efficiency with which engineering intelligence is converted into manufacturing reality. Even if the neutral CAD format can drive all the manufacturing machines, it would be meaningless unless the component description standard for CAD land patterns were implemented with some consistency. Zero component orientation has a key role in machine automation.

The obvious choice for global standardization for EE hardware engineering, PCB design layout, manufacturing, assembly and testing processes is to incorporate the standard land pattern conventions. Any other option continues the confusion and additional manual hours of intervention in order to achieve the goals of automation. In addition, the ease of having one system export a file so that another system can accomplish the work can require unnecessary manipulation of the neutral format in order to meet the object of clear, unambiguous software code.

The design of any assembly will continue to permit arrangement and orientation of components at any orientation consistent with design standards. Starting from a commonly understood data capture concept will benefit the entire supply chain.

This standard defines angle and origin point of land patterns for land pattern designing.

PRINTED BOARDS AND PRINTED BOARD ASSEMBLIES – DESIGN AND USE –

Part 7: Electronic component zero orientation for CAD library construction

1 Scope

This part of IEC 61188 establishes a consistent technique for the description of electronic component orientation, and their land pattern geometries. This facilitates and encourages a common data capture and transfer methodology amongst and between global trading partners.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61188-5 (all parts), *Printed boards and printed board assemblies – Design and use – Part 5-x: Attachment (land/joint) considerations*

3 Terms and definitions

No terms and definitions are listed in this document.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

4 Basic rules

4.1 Common rules

Common rules are divided into two groups: level A and level B. The main difference between the rules is the original orientation within the CAD system library. This orientation may be any version that the designer finds useful including his own version; however, when the information is transferred to an assembler, the orientation shall be properly defined without ambiguity or shall be corrected in order that any variation between the different systems are properly matched. This conversion of the CAD data to manufacturing information may include the datum of the board, fabrication panel or assembly array panel and shall have the proper orientation of all components on the board no matter what library was used as the original input.

4.2 General basic rules

The following basic rules apply.

- Components and land patterns are drawn in top view.
- The component point of origin is shown by "+" or "x".

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